

Piranha LEDs

LTL912SEKSA

**Selection Guide**

Part No.	Color	Φ_v (lm)	Va(deg.)	λ_d (nm)
LTL912SEKSA	Red	3.75	60	628

Benefits

- | Fewer LEDs Required
- | Lower lighting System Cost

Applications

- | Automotive Lighting
- | CHMSL
- | Stop Lamp
- | Rear Turn Signal Lamp
- | Front Turn Signal Lamp
- | Indirect Lighting
- | Signs and Signals

Features

- | High Current Operation
- | High Flux Output
- | Low Thermal Resistance
- | Low Profile
- | Wide Viewing Angle
- | Meet SAE/ ECE/ JIS Automotive Color Requirement
- | Tube Package for Automatic Loading and Insertion Process

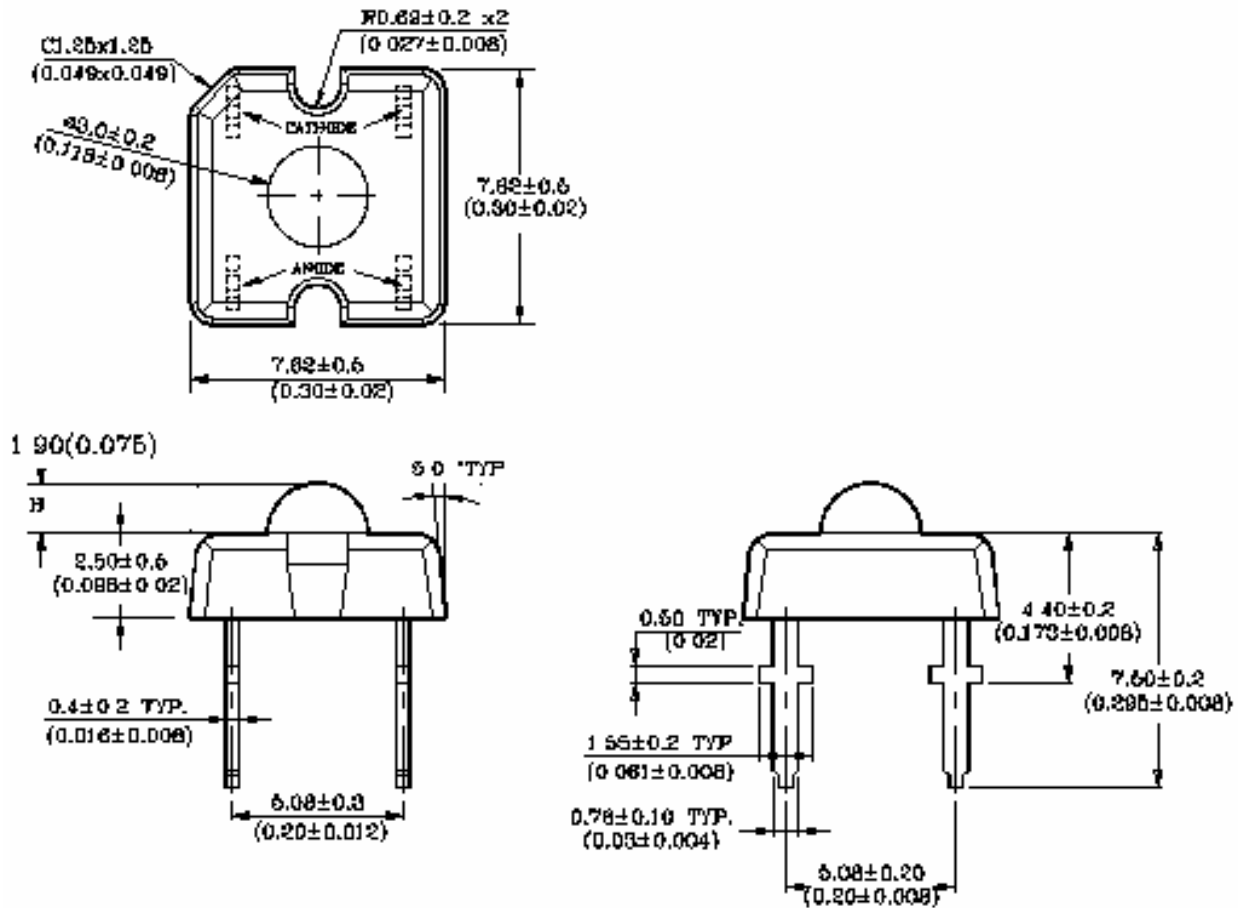
Description

These parts are designed for high current operation and high flux output applications. In order to solve the high temperature produced by the higher current operation, the package's design features better thermal management characteristics than other LED solutions coupled with an efficient optical design. This package design allows the lighting designer to reduce the number of LEDs required as well as the overall lighting system cost. The low profile package can be easily coupled to reflectors or lenses to efficiently distribute light and provide the desired illuminated appearance. This product family employs the world's brightest red, red-orange, amber, blue, cyan, green, and white LED materials etc., which allow designers to match the color of popular lighting applications, such as automotive lighting and electronic signs.

Devices

Part No.	Lens	Source Color
LTL912SEKSA	Water Clear	TS AlInGaP Red

Package Dimensions



NOTES:

1. All dimensions are in millimeters (inches).
2. Protruded resin is 1.0mm(.04") max.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject change to without notice.

Absolute Maximum Ratings at TA=25 °C

Parameter	AllInGaP <Note3>	Unit
Power Dissipation	242	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	100	mA
DC Forward Current	70	mA
AllInGaP Derating Linear From 60°C InGaN Derating Linear From 55 °C <Note2>	0.875	mA/°C
Reverse Voltage (I _r =100 μA)	10	V
Operating Temperature Range	-40°C to + 100°C	
Storage Temperature Range	-55°C to + 100°C	
LED Junction Temperature	125°C	
Soldering Preheat Temperature	100°C for 30 Seconds	
Lead Soldering Temperature	260°C for 5 Seconds [1.5mm (.06") From Seating Plane]	

Notes:

1. Operation at currents below 10mA is not recommended.
2. Derating linear as shown in Fig. 4
3. AllInGaP devices: LTL912SEKSA.

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Part No.	Min.	Typ.	Max.	Unit	Test Condition
Total Flux <Note1>	Φ_V	LTL912SEKSA	1.0	3.75		lm	IF=70mA
Luminous Intensity / Total Flux	I_v / Φ_V	LTL912SEKSA		0.9		cd /lm	IF=70mA
Viewing Angle <Note2, Fig 5>	$2\theta_{1/2}$	LTL912SEKSA		60		deg.	
Peak Emission Wavelength <Fig 1>	λ_P	LTL912SEKSA		638		nm	IF=70mA
Dominant Wavelength <Note 3>	λ_d	LTL912SEKSA	624	628	637	nm	IF=70mA
Forward Voltage	VF		2.19	2.50	3.39	V	IF=70mA
Reverse Voltage	VR		10	20		V	IR = 100 μ A
Thermal resistance	$R\theta_{J-PIN}$			125		°C /W	

- Note:
- Φ_V is the total luminous flux output as measured with an integrating sphere.
 - $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
 - The dominant wavelength, λ_d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

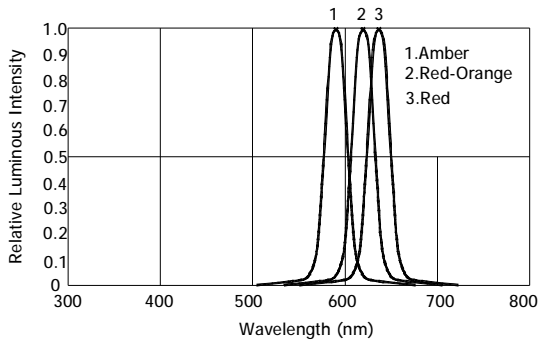


Fig.1 Relative Luminous Intensity vs. Wavelength

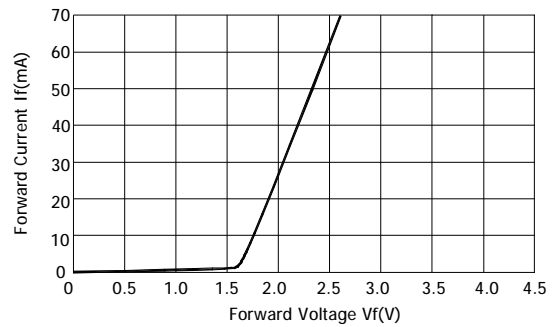


Fig.2 Forward Current vs. Forward Voltage

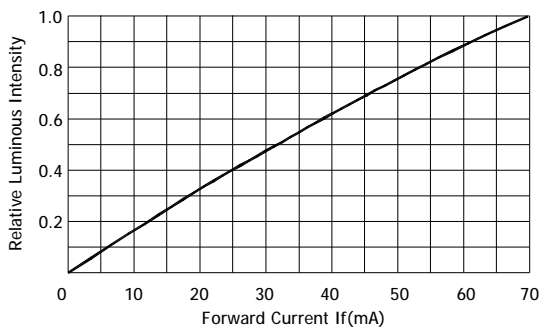


Fig.3 Relative Luminous Flux vs Forward Current

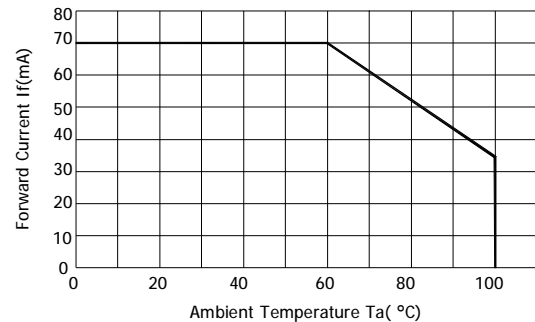


Fig.4 Forward Current vs. Ambient Temperature
($R_{\theta j-a}=300\text{ }^{\circ}\text{C/W}$)

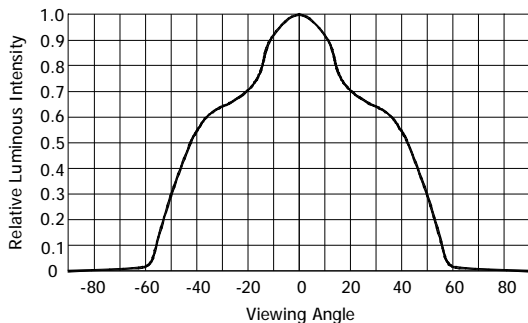


Fig.5a LTL911SxKSA
Relative Luminous Intensity vs. Viewing Angle

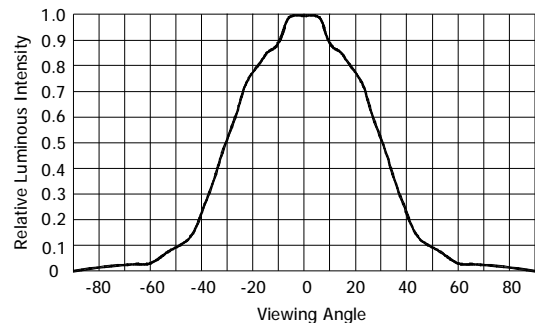


Fig.5b LTL912SxKSA
Relative Luminous Intensity vs. Viewing Angle

Bin Code List For Reference

Category Code		
F	4	

Luminous Flux
(Light-output; lm)
@ $I_F=70\text{mA}$, $T_A=25^\circ\text{C}$

Bin Code	Minimum	Maximum
3X	0.15	0.35
3Y	0.25	0.55
3Z	0.4	0.8
A	0.6	1.2
B	1.0	1.8
C	1.5	2.4
D	2.0	3.0
E	2.5	3.6
F	3.0	4.2
G	3.5	4.8
H	4.0	6.1
J	5.0	7.3
L	6.0	9.7

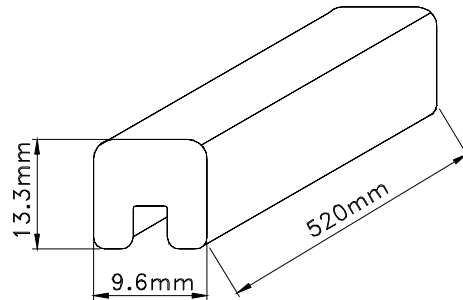
Forward Voltage
(Volt)
@ $I_F=70\text{mA}$, $T_A=25^\circ\text{C}$

Bin Code	Minimum	Maximum
1	2.19	2.43
2	2.31	2.55
3	2.43	2.67
4	2.55	2.79
5	2.67	2.91
6	2.79	3.03
7	2.91	3.15

Packing Spec

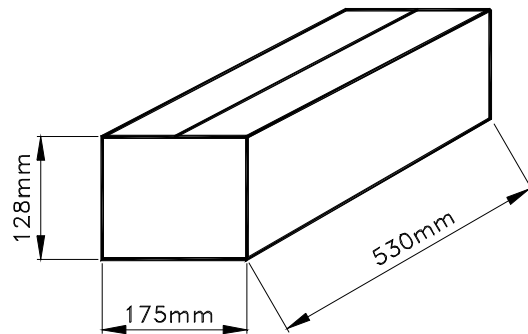
1. Tube: 65pcs

Dim: 520mm x 9.6mm x 13.3mm



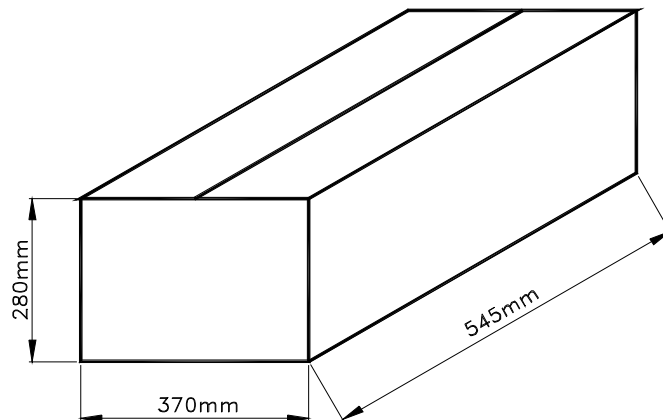
2. Inner carton: 153 tubes x 65 pcs = 9,945 pcs

Dim: 530mm x 175mm x 128mm



3. Outer carton: 4 inner cartons x 9,945 pcs = 39,780 pcs

Dim: 545mm x 370mm x 280mm



CAUTIONS

1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. Storage

The storage ambient for the LEDs should not exceed 30°C temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LEDs if necessary.

4. Lead Forming & Assembly

During lead forming, the leads should be bent at a point at least 3mm from the base of LED lens.

Do not use the base of the lead frame as a fulcrum during forming.

Lead forming must be done before soldering, at normal temperature.

During assembly on PCB, use minimum clinch force possible to avoid excessive mechanical stress.

5. Soldering

When soldering, leave a minimum of 2mm clearance from the base of the lens to the soldering point.

Dipping the lens into the solder must be avoided.

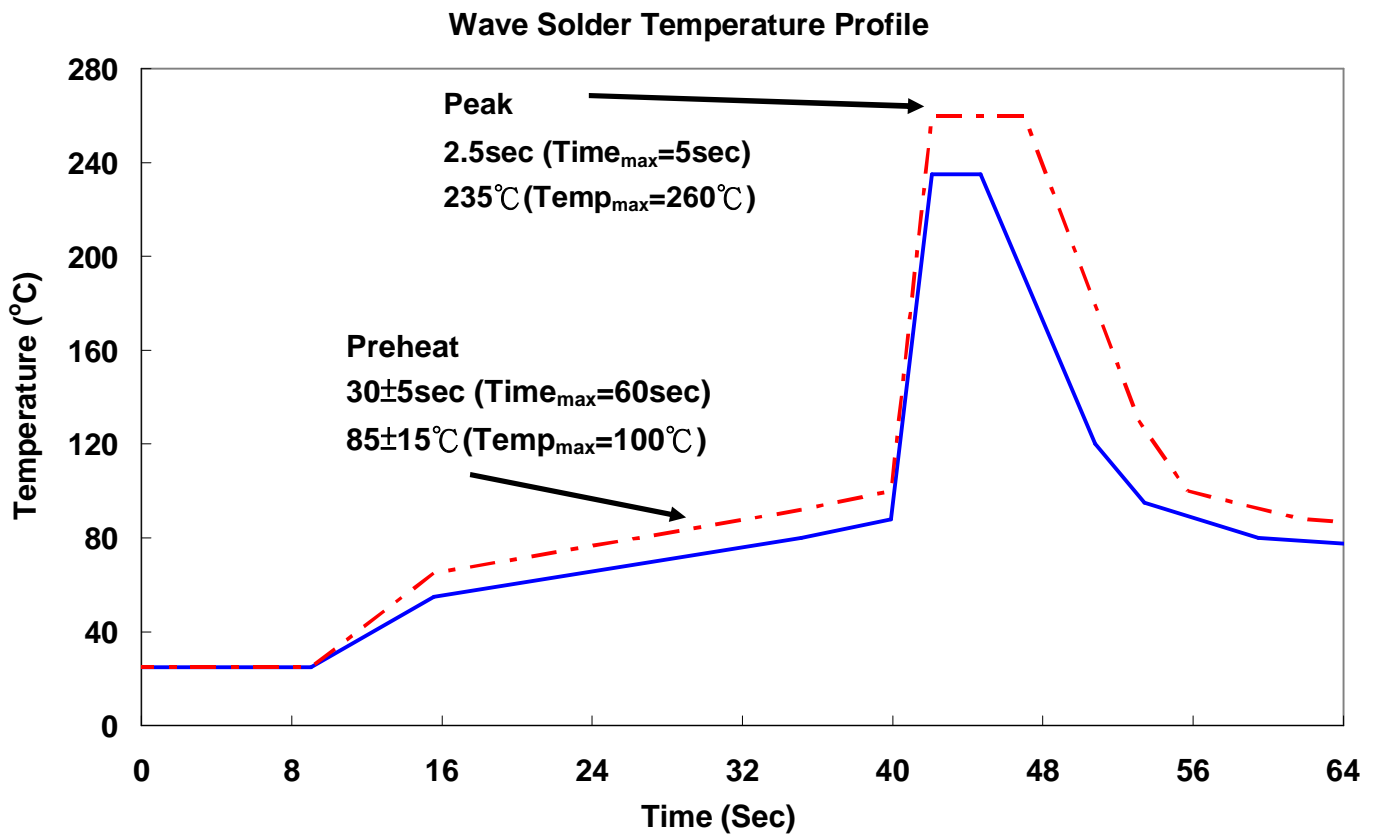
Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering conditions :

Soldering iron		Wave soldering	
Temperature	300°C Max.	Pre-heat	100°C Max.
Soldering time	3 sec. Max. (one time only)	Pre-heat time	60 sec. Max.
		Solder wave	260°C Max.
		Soldering time	5 sec. Max.

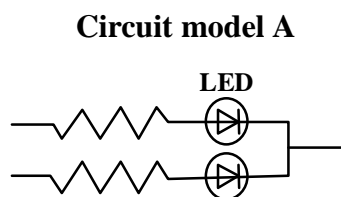
Note: Excessive soldering temperature and/or time might result in deformation of the LED lens or catastrophic failure of the LED. IR re-flow is not suitable process for through whole type Piranha LED production.

The suggesting soldering conditions are listed in table which is on page 9. The wave solder temperature profile which is showed as below figure is taken on the bottom side of the PCB board. Both of the suggesting and maximum conditions are all shown in the figure as below.

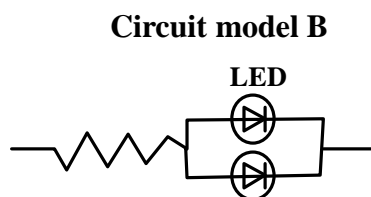


6. Drive Method

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



(A) Recommended circuit



(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

7. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use a conductive wrist band or anti- electrostatic glove when handling these LEDs
- All devices, equipment, and machinery must be properly grounded
- Work tables, storage racks, etc. should be properly grounded
- Use ion blower to neutralize the static charge which might have built up on surface of the LEDs plastic lens as a result of friction between LEDs during storage and handing

ESD-damaged Leeds will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or “no light up” at low currents. To verify for ESD damage, check for “light up” and Vf of the suspect LEDs at low currents.

The Vf of “good” LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AlInGaP product.

Chip ESD level	Machine Model	Human Body Model
InGaN / Sapphire	100 V	300 V
AlInGaP	200 V	500 V
InGaN / SiC	600 V	1000 V

Suggested checking list :**Training and Certification**

1. Everyone working in a static-safe area is ESD-certified?
2. Training records kept and re-certification dates monitored?

Static-Safe Workstation & Work Areas

1. Static-safe workstation or work-areas have ESD signs?
2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
3. All ionizer activated, positioned towards the units?
4. Each work surface mats grounding is good?

Personnel Grounding

1. Every person (including visitors) handling ESD sensitive (ESDS) items wear wrist strap, heel strap or conductive shoes with conductive flooring?
2. If conductive footwear used, conductive flooring also present where operator stand or walk?
3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?
4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DSL?
5. All wrist strap or heel strap checkers calibration up to date?

Note: *50V for Blue LED.

Device Handling

1. Every ESDS items identified by EIA-471 labels on item or packaging?
2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
4. All flexible conductive and dissipative package materials inspected before reuse or recycle?

Others

1. Audit result reported to entity ESD control coordinator?
2. Corrective action from previous audits completed?
3. Are audit records complete and on file?

8. Others

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